

Description

The IRFR3410 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



TO-252-2L

General Features

$V_{DS} = 100V$ $I_D = 30A$

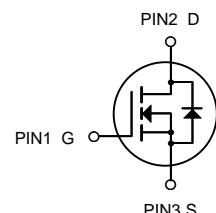
$R_{DS(ON)} < 48m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

| Product ID | Pack | Brand | Qty(PCS) |
|------------|-----------|-------------|----------|
| IRFR3410 | TO-252-2L | EVVO MOSFET | 2500 |

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-------------------------|---|------------|-------|
| V_{DS} | Drain-Source Voltage | 100 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D @ T_c=25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 30 | A |
| $I_D @ T_c=100^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 13 | A |
| I_{DM} | Pulsed Drain Current ² | 80 | A |
| EAS | Single Pulse Avalanche Energy ³ | 30 | mJ |
| $P_D @ T_c=25^\circ C$ | Total Power Dissipation ⁴ | 42 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | °C |
| T_J | Operating Junction Temperature Range | -55 to 150 | °C |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | 3.6 | °C/W |

N-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|--|--|------|------|-----------|------------------|
| Off Characteristic | | | | | | |
| $V_{(\text{BR})\text{DSS}}$ | Drain-Source Breakdown Voltage | $V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$ | 100 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{\text{DS}}=100\text{V}$, $V_{\text{GS}}=0\text{V}$, | - | - | 1.0 | μA |
| I_{GSS} | Gate to Body Leakage Current | $V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=\pm 20\text{V}$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| $V_{\text{GS}(\text{th})}$ | Gate Threshold Voltage | $V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$ | 1.0 | 1.5 | 2.2 | V |
| $R_{\text{DS}(\text{on})}$ note3 | Static Drain-Source on-Resistance | $V_{\text{GS}}=10\text{V}$, $I_D=10\text{A}$ | - | 37 | 48 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}$, $I_D=6\text{A}$ | - | 39 | 55 | $\text{m}\Omega$ |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1.0\text{MHz}$ | - | 1964 | - | pF |
| C_{oss} | Output Capacitance | | - | 90 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 74 | - | pF |
| Q_g | Total Gate Charge | $V_{\text{DS}}=80\text{V}$, $I_D=20\text{A}$, $V_{\text{GS}}=4.5\text{V}$ | - | 20 | - | nC |
| Q_{gs} | Gate-Source Charge | | - | 3.1 | - | nC |
| Q_{gd} | Gate-Drain("Miller") Charge | | - | 14 | - | nC |
| Switching Characteristics | | | | | | |
| $t_{\text{d}(\text{on})}$ | Turn-on Delay Time | $V_{\text{DS}}=80\text{V}$, $I_D=20\text{A}$, $R_G=3.1\Omega$, $V_{\text{GS}}=4.5\text{V}$ | - | 11 | - | ns |
| t_r | Turn-on Rise Time | | - | 91 | - | ns |
| $t_{\text{d}(\text{off})}$ | Turn-off Delay Time | | - | 40 | - | ns |
| t_f | Turn-off Fall Time | | - | 71 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I_s | Maximum Continuous Drain to Source Diode Forward Current | - | - | 27 | - | A |
| I_{SM} | Maximum Pulsed Drain to Source Diode Forward Current | - | - | 80 | - | A |
| V_{SD} | Drain to Source Diode Forward Voltage | $V_{\text{GS}}=0\text{V}$, $I_s=20\text{A}$ | - | - | 1.2 | V |
| trr | Body Diode Reverse Recovery Time | $I_F=20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$ | - | 64 | - | ns |
| Q_{rr} | Body Diode Reverse Recovery Charge | | - | 152 | - | nC |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=50\text{V}$, $V_G=10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$, $I_{\text{AS}}= 11\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

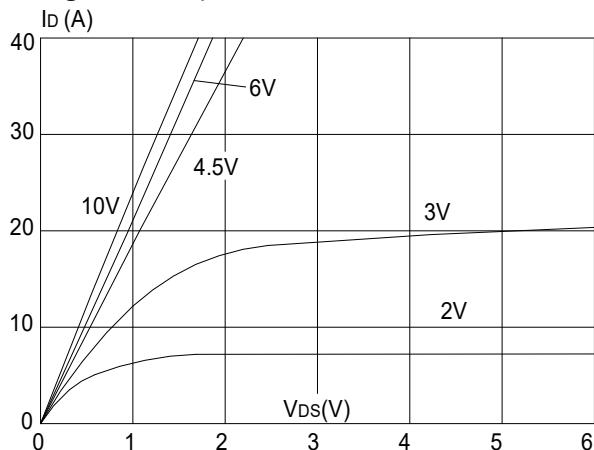


Figure 2: Typical Transfer Characteristics

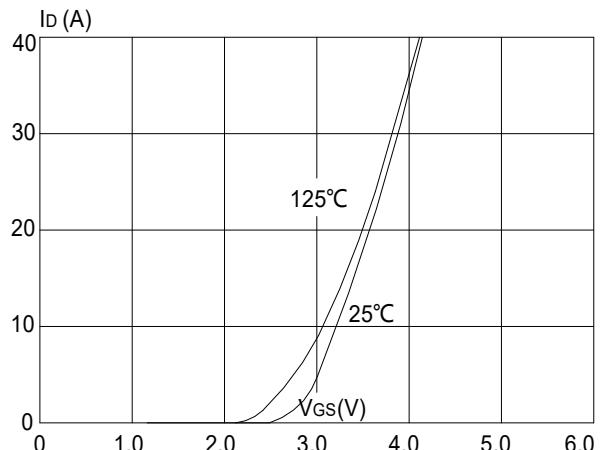


Figure 3: On-resistance vs. Drain Current

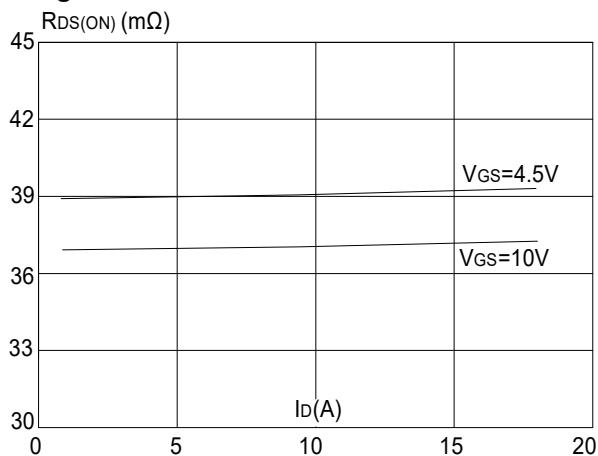


Figure 4: Body Diode Characteristics

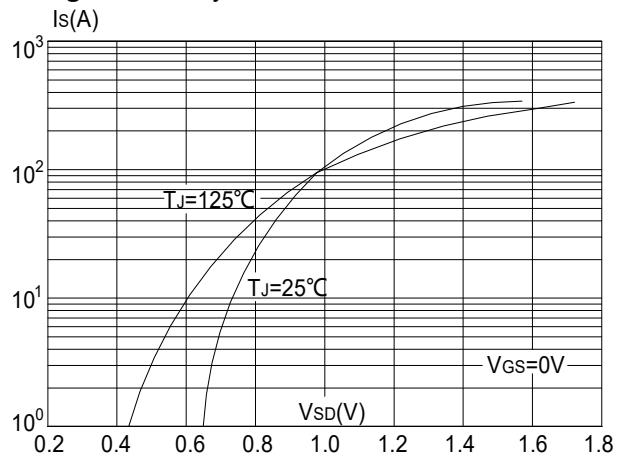


Figure 5: Gate Charge Characteristics

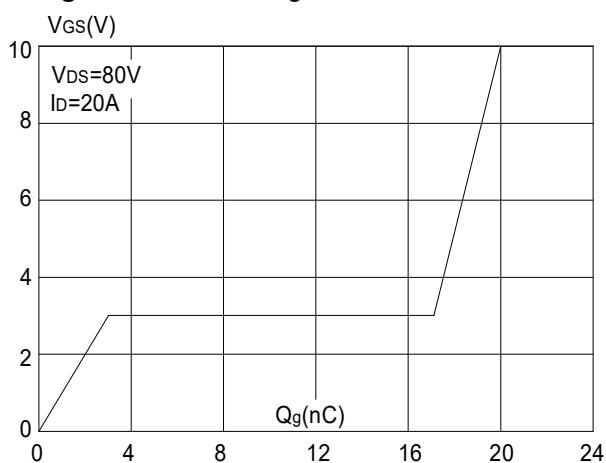


Figure 6: Capacitance Characteristics

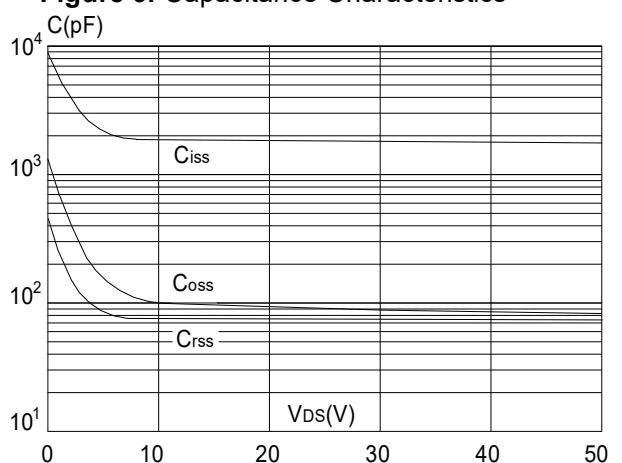


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

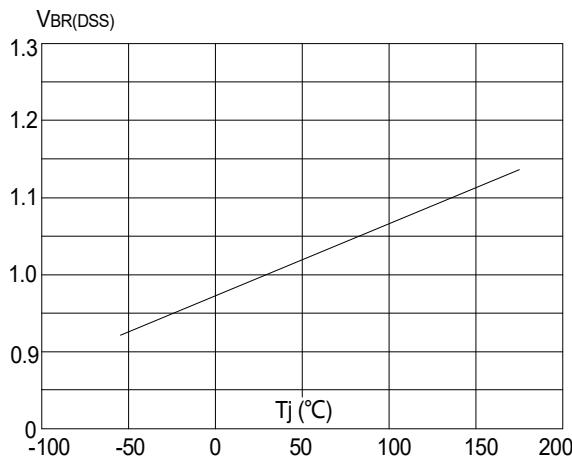


Figure 8: Normalized on Resistance vs. Junction Temperature

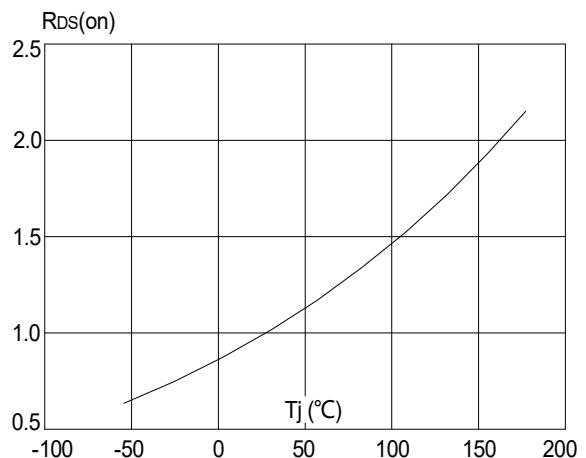


Figure 9: Maximum Safe Operating Area

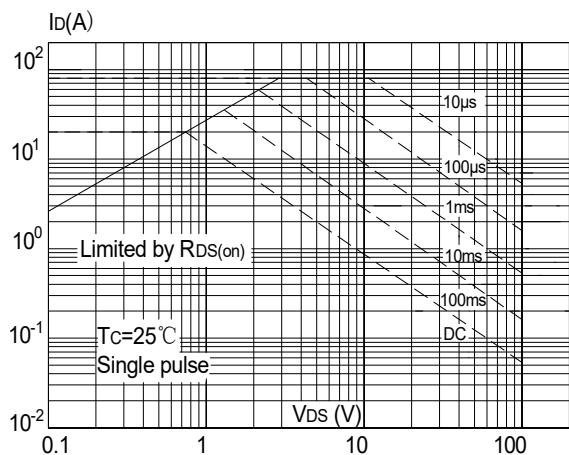


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

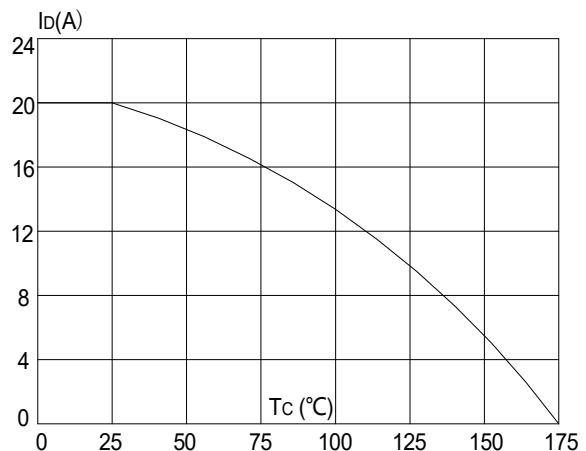
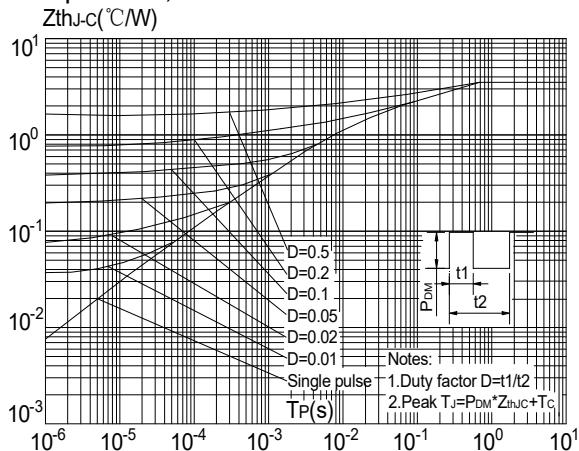
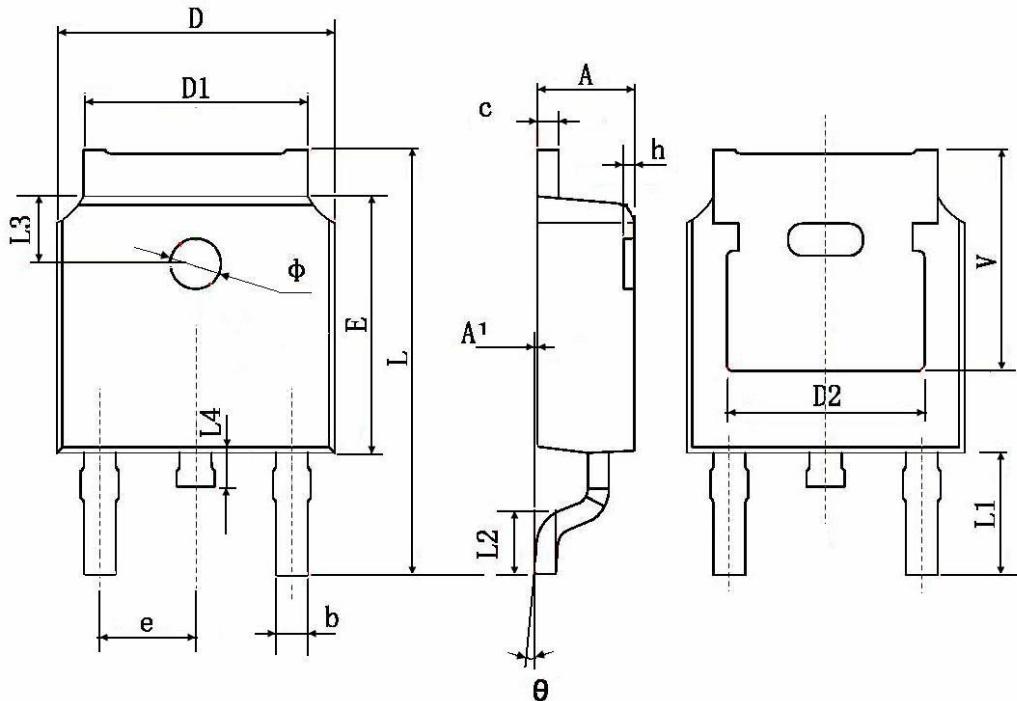


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



TO-252-2L Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.200 | 2.400 | 0.087 | 0.094 |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 |
| b | 0.660 | 0.860 | 0.026 | 0.034 |
| c | 0.460 | 0.580 | 0.018 | 0.023 |
| D | 6.500 | 6.700 | 0.256 | 0.264 |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 |
| D2 | 0.483 TYP. | | 0.190 TYP. | |
| E | 6.000 | 6.200 | 0.236 | 0.244 |
| e | 2.186 | 2.386 | 0.086 | 0.094 |
| L | 9.800 | 10.400 | 0.386 | 0.409 |
| L1 | 2.900 TYP. | | 0.114 TYP. | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 |
| L3 | 1.600 TYP. | | 0.063 TYP. | |
| L4 | 0.600 | 1.000 | 0.024 | 0.039 |
| Φ | 1.100 | 1.300 | 0.043 | 0.051 |
| θ | 0° | 8° | 0° | 8° |
| h | 0.000 | 0.300 | 0.000 | 0.012 |
| V | 5.350 TYP. | | 0.211 TYP. | |